

**PATENT**

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

IN RE APPLICATION OF: BOON SUAN JEUNG *ET AL.*  
FILED: CONCURRENTLY HEREWITH  
FOR: **MULTI-SUBSTRATE  
MICROELECTRONIC PACKAGES AND  
METHODS FOR MANUFACTURE**

**Preliminary Amendment**

Mail Stop Patent Application  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Dear Commissioner:

Prior to examination on the merits, please amend the above-identified application as follows:

Amendments to the Specification begin on page 2.

Amendments to the Claims are reflected in the listing of claims beginning on page 3.